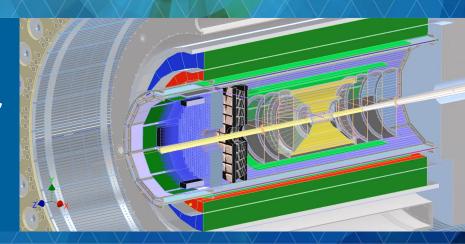
ePIC Calorimetry Meeting

# Barrel Imaging Calorimeter ePIC TDR Planning



05/15/2024



### **TDR Structure**

ready to write partially ready to write lots of to do

### Design

- Overview
- Detector Requirements

#### Performance

- Performance with most up to date geometry/envelopes \*\*
  - Energy resolution, Position resolution,
  - o e/pi separation, gamma/pi0 separation
- Beam test benchmarking (e resolution)
- Literature benchmarking (pion response)
- Backgrounds

### Sector Design, Mechanics and Integration

- Sector design and construction
- Tracker mechanics X
- End-of-sector box mechanics
- Deflection studies
- Barrel assembly and integration tooling

#### AstroPix Wafers & Modules

- AstroPix characteristics and readiness \( \sqrt{\lambda} \) \( \lambda \righta \)
- Automated wafer testing
- Module & stave design
- Stave bus design
- Module assembly and scalability \*\*

#### End-of-sector Box and Readout

- SiPMs characteristics \( \sqrt{\psi} \) \( \frac{\psi}{\psi} \)
- SiPM boards and FEB ////
- 🕨 LED system 🌠/🚧
- Tracker End-of-tray card (RDO)
- Slow controls (temperature, humidity)

### Cooling

- Cooling system design
- Global heat load simulations

#### System Testing

- System Calibration X
- System QC
- System Demonstration 🚧/🔭





### **Performance**

#### Performance

- Performance with most up to date geometry/envelopes
  - a. Energy resolution, Position resolution,
  - b. e/pi separation, gamma/pi0 separation
- 2. Beam test benchmarking (e resolution) 🚧
- 3. Literature benchmarking (pion response) 🚧
- 4. Backgrounds 💥

Tasks	Time	Missing Workforce/Resources
1a and 1b	June 2024 (repeated depending on implementation of design)	FTEs on reconstruction algorithms implementation and validation.
2	August 2024	
3	October 2024 (depending on beam test success)	
4	November 2024	Requires input from background task-force and work on reconstruction algorithms.

# **System Testing**

- 1. System Calibration 💥
- 2. System QC 💥
- 3. System Demonstration <a href="#">
  </a>/
  <a href="#">
  <a href="#">

Tasks	Time	Missing Workforce/Resources
1, 2	July 2024 Internal preliminary design review Sep 2024 Preliminary design review May 2025 Internal final design review	
3	May 2024 FTBF Beamtest (Commissioning, e/pion response) September 2024 First Integrated Mechanical Test Article Nov/Dec 2024 FTBF Beamtest (Integrations, e/pion response) July 2025 Large Integrated Test Article	

# Sector Design, Mechanics and Integration

- Sector design and construction
- 2. Tracker mechanics X
- End-of-sector box mechanics
- 4. Deflection studies 💥
- Barrel assembly and integration tooling

Tasks	Time	Missing Workforce/Resources
1,2,3	July 2024 Internal preliminary design Sep 2024 Preliminary design review Jan 2025 Internal final design review	
4	July 2024 Sector-scale FEA Dec 2024 Full system FEA	
5	May 2024 Assembly Strategy Decision (w/ Project) Dec 2024 Assembly and tooling design	

### **End-of-sector Box and Readout**

- 1. SiPMs characteristics ✓///
- 2. SiPM boards and FEB 🚧/💥
- LED system
- 4. Tracker End-of-tray card (RDO)
- Slow controls (temperature, humidity)

Tasks	Time	Missing Workforce/Resources
1	July 2024 Irradiation Studies (FBTF tests) Sep 2024 Start Bidding/Procurement	
2, 3, 4, 5	July 2024 Internal preliminary design Sep 2024 Preliminary design review Mar 2025 Internal final design review	Formal FEB expert (Norbert has been helping us)

# Cooling

- Cooling system design
- 2. Global heat load simulations 🗶

Tasks	Time	Missing Workforce/Resources
1, 2	July 2024 Internal preliminary design Sep 2024 Preliminary design review Jan 2025 Internal final design review	TBD: FEA expert to conduct simulations (can recruit from BIC DSC or maybe get help from Project)

### **AstroPix Wafers & Modules**

- AstroPix characteristics and readiness \( \sqrt{\psi} \) / \( \sqrt{\psi} \)
- Automated wafer testing
- 3. Module & stave design 🚧
- 4. Stave bus design 💥
- Module assembly and scalability \*

Tasks	Time	Missing Workforce/Resources
1	Nov 2024 AstroPix v5 characterization June 2025 AstroPix v6 characterization (production chip)	
2	Jul 2024 chip-level QC testing for AstroPix v3 Nov 2024 chip-level QC testing for AstroPix v5 Jan 2025 transition from chip to wafer-level QC testing	
3,4,5	July 2024 Internal preliminary design Sep 2024 Preliminary design review Apr 2025 Internal final design review	





# In-person BIC Workshop - May 14-17, 2024

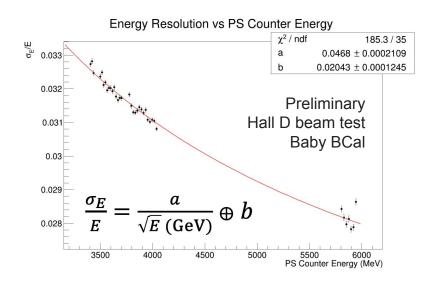
### https://indico.bnl.gov/event/22517/timetable/

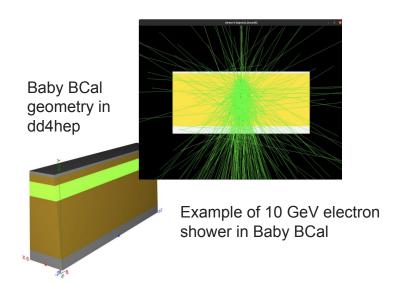
- Day 1: Updates on ongoing R&D and simulation work
- Day 2: Summary of the status of global, end-of-sector box, and AstroPix module interfaces and work on rev. 1 interfaces documents
- Day 3: Interfaces documentation and detailed PED work planning
- Day 4: Prototypes and test articles planning



# **Performance and System Testing**

- 1. Most up to date detector envelopes included in the simulation <a href="https://github.com/eic/epic/pull/729">https://github.com/eic/epic/pull/729</a>
- 2. Update during the BIC in Person Workshop (May 14-17) on electron energy resolution from Hall-D beam test in 2023 and simulations
  - J. Zharling: https://indico.bnl.gov/event/22517/contributions/91532/
  - J. Richards: https://indico.bnl.gov/event/22517/contributions/91533/





### **Performance and System Testing**

- 3. Update on ongoing beam cosmics test in Fermilab Beam Test Facility (May 8-14)
- H. Klest, M. Zurek, B. Kim: <a href="https://indico.bnl.gov/event/22517/contributions/91530/">https://indico.bnl.gov/event/22517/contributions/91530/</a>,

https://indico.bnl.gov/event/22517/contributions/91531/, https://indico.bnl.gov/event/22517/contributions/91624/

- AstroPix and Baby BCal (SciFi/Pb) installed and tested with cosmics in the FBTF
- Based on performed tests further ongoing efforts to fully readout the Baby BCal (+other FTBF detectors and cosmic paddles) in the same data stream
- No beam delivered to FBTF so far as of today. Possibility of one week of June 12.
- Goal:
  - Fully commission the setup with the beam including the first test of the integration between AstroPix and SciFi/Pb.
  - Benchmark response to pions.

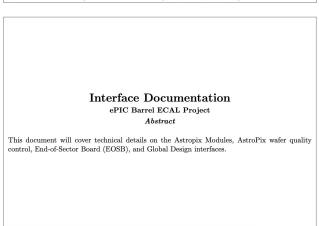


Telescope Setup

# Sector Design, Mechanics and Integration

- 1. Extensive work on finalizing **revision 1 of the interfaces document for BIC** over the last few months, with a series of topical meetings and writing sessions during the in-person BIC Workshop.
- 2. **Freezing interfaces** as PED funds become available to some of our collaborators will allow teams to **focus on sub-component designs** with clearly defined envelopes and conditions





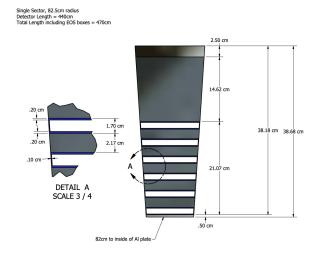


Figure 2: Single Sector, End View. Sectors build of the layers of scintillating fibers embedded in lead shown in gray and 6 slots for AstroPix layers shown in white.

### **End of Sector Box**

1. Finalizing mechanical interfaces for the designs of SiPM and HGCROC PCB, end-of-tray card (AstroPix FPGA), cooling, lightguides, connectors, etc.

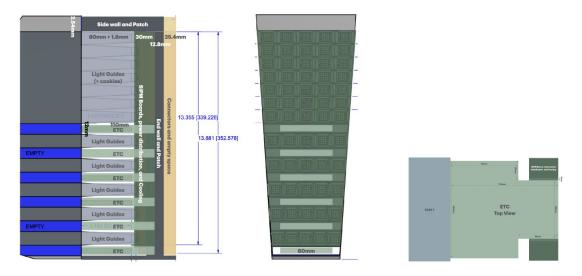


Figure 11: Napkin sketch of the mechanical envelopes for the ESB. Left: Side view in the middle of a sector. Center: Rear view cutout at the SiPM PCB Right: Top view of the AstroPix readout FPGA. **TODO:** replace with engineering drawings

### **AstroPix Wafers & Modules**

- 1. See the presentation by Manoj Jadhav (TIC Meeting, May 20) on AstroPix Update
- 2. AstroPix v5 status (to be submitted for an engineering run in June) at the BIC in-person meeting: Nicolas Striebig <a href="https://indico.bnl.gov/event/22517/contributions/91071/">https://indico.bnl.gov/event/22517/contributions/91071/</a>
- 3. Developments towards wafer testing in Korea: Sanghoon Lim: <a href="https://indico.bnl.gov/event/22517/contributions/91072/">https://indico.bnl.gov/event/22517/contributions/91072/</a>

Probe card for ALPIDE

a. Initial version of AstroPix v3 probe card for the carrier card only expected in a few weeks

